

[Document Name] Abstract

[Abstract]

[Object] The object of the present invention is to provide a free and precise control of the plating amount while easily determining a selected portion to be plated.

[Means for Solution] Metal small balls 4 are arranged at, and adhered or bonded to, leads of copper wiring 2 of a glass-epoxy substrate 1 and the metal small balls 4 are then melted so that the leads of copper wiring 2 of the glass-epoxy substrate is selectively coated with a different metal, thereby facilitating partially plating selected portions of a substrate for electronic devices easily and precisely.

[Selected Drawing] Fig. 1



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